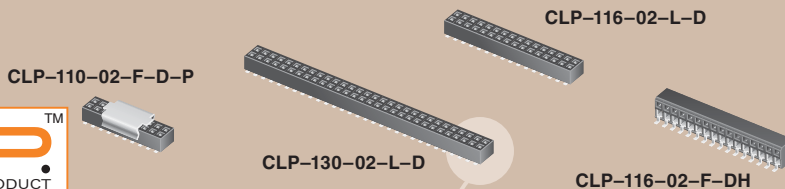




(1,27mm) .050"

CLP SERIES



LOW PROFILE DUAL WIPE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

Insulator Material: Black Liquid Crystal Polymer



Contact Material: Phosphor Bronze
Plating: Sn or Au over 50µm (1,27µm) Ni

Current Rating: 1.75A @ 80°C ambient
Operating Temp Range: -55°C to +125°C

Contact Resistance: 10 mΩ max

Insertion Depth: Top Entry = (1,40mm) .055" minimum, Bottom Entry = (2,41mm) .095" minimum plus board thickness
DH Entry = (2,31mm) .091" to (2,67mm) .105"

Insertion Force: (Single contact only) 3.8oz (1,05N) average

Normal Force: 60 grams (0,59N) average

Withdrawal Force: (Single contact only) 2oz (0,56N) average

Max Cycles: 100 with 10µm (0,25µm) Au
RoHS Compliant: Yes

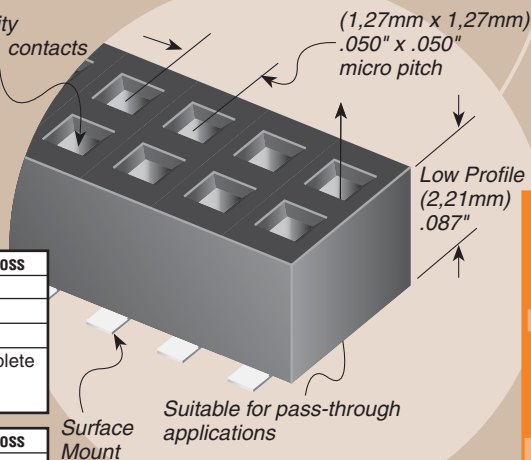
Processing: Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0,10mm) .004" max (02-35) (0,15mm) .006" max (36-50)

Mates with: FTSH, FTS, FW, FFDL2



High reliability Tiger Claw™ contacts



1,27mm FTSH/CLP	Rated @ 3dB Insertion Loss
5,13mm Stack Height	
Single-Ended Signaling	7.0 GHz / 14 Gbps
Differential Pair Signaling	8.5 GHz / 17 Gbps

Performance data for other stack heights and complete test data available at www.samtec.com?CLP or contact sig@samtec.com

1,27mm FW/CLP	Rated @ 3dB Insertion Loss
17,7mm Stack Height	
Single-Ended Signaling	3.0 GHz / 6.0 Gbps
Differential Pair Signaling	4.0 GHz / 8.0 Gbps

Performance data for other stack heights and complete test data available at www.samtec.com?CLP or contact sig@samtec.com

APPLICATIONS



CLP - **1** NO. PINS PER ROW - **02**

02 thru 50

PLATING OPTION

- F = Gold flash on contact, Matte Tin on tail
- L = 10µm (0,25µm) Gold on contact, Matte Tin on tail
- G = 10µm (0,25µm) Gold (-D only)

ROW OPTION

- D = Double Row
- DH = Double Horizontal (Requires FTSH or FSH -01 lead style)

OTHER OPTION

- BE = Bottom Entry (Required for bottom entry applications)
- A = Alignment Pin (Not available with -PA option) (5, 10, 25 position only) (-DH option and other sizes. Call Samtec)
- K = (4,00mm) .157" DIA Polyimide film Pick & Place Pad (5 positions min.)
- P = Pick & Place Pad (5 positions min. -D only) (Not always necessary for auto placement. See Flex Processing.)
- PA = Pick & Place Pad with Alignment Pin (-D only) (Not Available with -A option)
- TR = Tape & Reel

PIN/ROW	A
04-15	(3,56) .140
16-50	(7,11) .280

If odd pins/row, alignment pins are on middle position on centerline of the part. If even pins/row, then alignment pins are between middle two positions.

ALSO AVAILABLE

Single row available. (Mates with FTS Series) Call Samtec.

APPLICATION SPECIFIC OPTION

Single row options available. Call Samtec.

Note: Other Gold plating options available. Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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